



Spec	Type	Base Thickness	Processed Thickness	RC	DK
ENIG		0.005			
		0.020			
	Signal	0.018	0.018		
FR4 · 2116	Prepreg	0.13	0.1195	52%	4.3
	Signal	0.035	0.035		
FR4 · 2116	Prepreg	0.114	0.53	52%	4.3
	Plane	0.035	0.035		
FR4 · 2116	Prepreg	0.13	0.109	52%	4.3
	Core	0.53	0.53		4.7
	Plane	0.035	0.035		
	Core	0.53	0.53		
	Plane				
FR4	Core	0.13	0.109	52%	4.3
	Plane	0.035	0.035		
FR4 · 1080	Prepreg	0.53	0.53	65%	4.6
	Signal	0.035	0.035		
FR4	Core	0.5	0.5	56%	4.2
	Signal	0.018	0.018		
		0.020			
ENIG		0.005			

8 Layer Traditional Symmetric

Thickness After Lamination: 3.168 mm
 Finished PCB Thickness: 3.218 mm ±10%
 Inner layer Residual copper ratio: 70%